

LOWER ELECTRODE DESIGN FOR HIGHER UNIFORMITY

Abstract of the Disclosure

5 A plasma processing system for processing a substrate is disclosed. The
plasma processing system includes a process chamber within which a plasma is both
ignited and sustained for processing. The plasma processing system further includes
an electrode disposed at the lower end of the process chamber. The electrode is
configured for generating an electric field inside the process chamber. The plasma
10 processing system also includes a component for controlling an impedance between
the electrode and the plasma. The impedance is arranged to affect the electric field to
improve processing uniformity across the surface of the substrate.

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